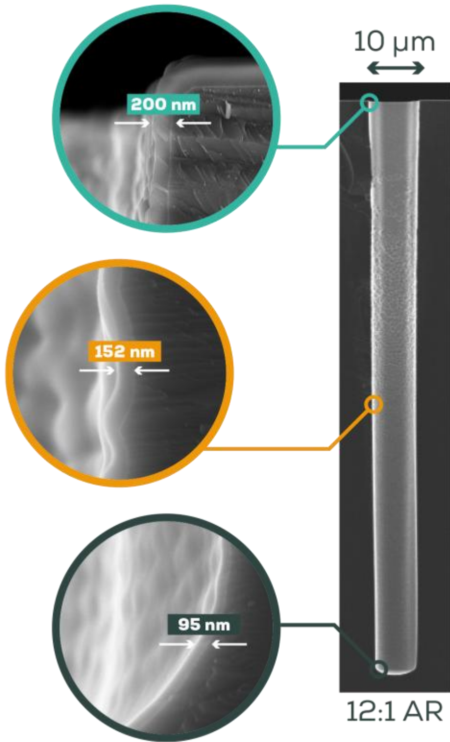
KOBUS
Process like no one

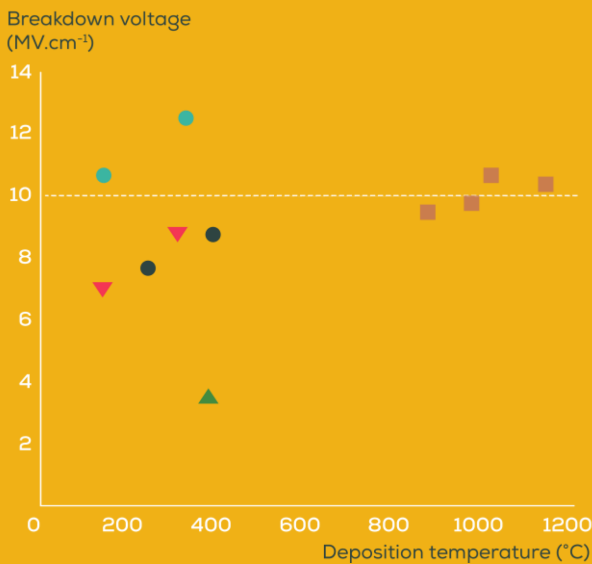
F.A.S.T.® for TSV

SiO_2 liner solution

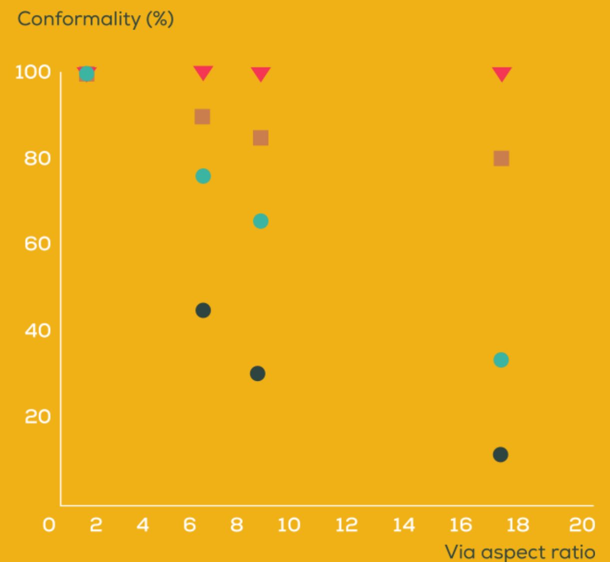


- One solution for both via middle & via last
- Conformality adjustable to integration request
- High deposition rate (> 50 nm/min)
- 200 & 300 mm single wafer cluster tools
- High throughput solution
- Low cost of ownership

ISOLATION PERFORMANCES @ LOW TEMPERATURE



BEST COMPROMISE DEPOSITION RATE/CONFORMALITY



10x faster than ALD
3x higher conformality than PECVD

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